

NSBA143EDXV6T1G Datasheet



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DiGi Electronics Part Number NSBA143EDXV6T1G-DG

Manufacturer onsemi

Manufacturer Product Number NSBA143EDXV6T1G

Description TRANS PREBIAS 2PNP 50V SOT563

Detailed Description Pre-Biased Bipolar Transistor (BJT) 2 PNP - Pre-Bias ed (Dual) 50V 100mA 500mW Surface Mount SOT-5

62



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RFQ Email: Info@DiGi-Electronics.com

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Purchase and inquiry

Manufacturer Product Number:	Manufacturer:
NSBA143EDXV6T1G	onsemi
Series:	Product Status:
	Active
Transistor Type:	Current - Collector (Ic) (Max):
2 PNP - Pre-Biased (Dual)	100mA
Voltage - Collector Emitter Breakdown (Max):	Resistor - Base (R1):
50V	4.7kOhms
Resistor - Emitter Base (R2):	DC Current Gain (hFE) (Min) @ Ic, Vce:
4.7kOhms	15 @ 5mA, 10V
Vce Saturation (Max) @ lb, lc:	Current - Collector Cutoff (Max):
250mV @ 1mA, 10mA	500nA
Frequency - Transition:	Power - Max:
	500mW
Mounting Type:	Package / Case:
Surface Mount	SOT-563, SOT-666
Supplier Device Package:	Base Product Number:
SOT-563	NSBA143

Environmental & Export classification

8541.21.0095

RoHS Status:	Moisture Sensitivity Level (MSL):
ROHS3 Compliant	1 (Unlimited)
REACH Status:	ECCN:
REACH Unaffected	EAR99
HTSUS:	



Dual PNP Bias Resistor Transistors R1 = 4.7 k Ω , R2 = 4.7 k Ω

MUN5132DW1, NSBA143EDXV6, NSBA143EDP6

PNP Transistors with Monolithic Bias Resistor Network

This series of digital transistors is designed to replace a single device and its external resistor bias network. The Bias Resistor Transistor (BRT) contains a single transistor with a monolithic bias network consisting of two resistors; a series base resistor and a base–emitter resistor. The BRT eliminates these individual components by integrating them into a single device. The use of a BRT can reduce both system cost and board space.

Features

- S and NSV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- Simplifies Circuit Design
- Reduces Board Space
- Reduces Component Count
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant

MAXIMUM RATINGS

(T_A = 25°C, common for Q1 and Q2, unless otherwise noted)

Rating	Symbol	Max	Unit
Collector-Base Voltage	V _{CBO}	50	Vdc
Collector-Emitter Voltage	V_{CEO}	50	Vdc
Collector Current – Continuous	I _C	100	mAdc
Input Forward Voltage	$V_{IN(fwd)}$	30	Vdc
Input Reverse Voltage	V _{IN(rev)}	10	Vdc

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

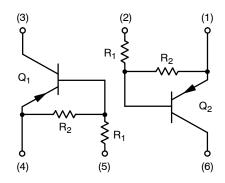
ORDERING INFORMATION

Device	Package	Shipping [†]
MUN5132DW1T1G	SOT-363	3,000 / Tape & Reel
NSBA143EDXV6T1G	SOT-563	4,000 / Tape & Reel
NSBA143EDP6T5G	SOT-963	8,000 / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

1

PIN CONNECTIONS



MARKING DIAGRAMS





SOT-363 CASE 419B





SOT-563 CASE 463A





SOT-963 CASE 527AD

OJ/F = Specific Device Code M = Date Code*

= Pb-Free Package
 (Note: Microdot may be in either location)

*Date Code orientation may vary depending upon manufacturing location.

THERMAL CHARACTERISTICS

	Characteristic	Symbol	Max	Unit
MUN5132DW1 (SOT-363) On	e Junction Heated			
Total Device Dissipation $T_A = 25^{\circ}C \qquad (Note 1)$ $(Note 2)$ Derate above 25°C $(Note 2)$	(Note 1)	P _D	187 256 1.5 2.0	mW mW/°C
Thermal Resistance, Junction to Ambient	(Note 1) (Note 2)	$R_{ hetaJA}$	670 490	°C/W
MUN5132DW1 (SOT-363) Bo	th Junction Heated (Note 3)			
Total Device Dissipation T _A = 25°C (Note 1) (Note 2) Derate above 25°C (Note 2)	(Note 1)	P _D	250 385 2.0 3.0	mW mW/°C
Thermal Resistance, Junction to Ambient	(Note 1) (Note 2)	$R_{ hetaJA}$	493 325	°C/W
Thermal Resistance, Junction to Lead (Note 2)	(Note 1)	$R_{ hetaJL}$	188 208	°C/W
Junction and Storage Temper	ature Range	T _J , T _{stg}	-55 to +150	°C
NSBA143EDXV6 (SOT-563)	One Junction Heated	<u> </u>		
Total Device Dissipation $T_A = 25^{\circ}C$ (Note 1) Derate above 25°C	(Note 1)	P _D	357 2.9	mW mW/°C
Thermal Resistance, Junction to Ambient	(Note 1)	$R_{ hetaJA}$	350	°C/W
NSBA143EDXV6 (SOT-563) I	Both Junction Heated (Note 3)	•		
Total Device Dissipation T _A = 25°C (Note 1) Derate above 25°C	(Note 1)	P _D	500 4.0	mW mW/°C
Thermal Resistance, Junction to Ambient	(Note 1)	$R_{ hetaJA}$	250	°C/W
Junction and Storage Temper	ature Range	T _J , T _{stg}	-55 to +150	°C
NSBA143EDP6 (SOT-963) O	ne Junction Heated			
Total Device Dissipation T _A = 25°C (Note 4) (Note 5) Derate above 25°C (Note 5)	(Note 4)	P _D	231 269 1.9 2.2	mW mW/°C
Thermal Resistance, Junction to Ambient	(Note 4) (Note 5)	$R_{ hetaJA}$	540 464	°C/W
NSBA143EDP6 (SOT-963) Be	oth Junction Heated (Note 3)	L		
Total Device Dissipation $T_A = 25^{\circ}C \qquad \text{(Note 4)}$ (Note 5) Derate above 25°C (Note 5)	(Note 4)	P _D	339 408 2.7 3.3	mW mW/°C
Thermal Resistance, Junction to Ambient	(Note 4) (Note 5)	$R_{ hetaJA}$	369 306	°C/W
Junction and Storage Temper	ature Range	T _J , T _{stg}	-55 to +150	°C

- FR-4 @ Minimum Pad.
 FR-4 @ 1.0 x 1.0 Inch Pad.
 Both junction heated values assume total power is sum of two equally powered channels.
 FR-4 @ 100 mm², 1 oz. copper traces, still air.
 FR-4 @ 500 mm², 1 oz. copper traces, still air.

ELECTRICAL CHARACTERISTICS ($T_A = 25$ °C, common for Q_1 and Q_2 , unless otherwise noted)

Characteristic	Symbol	Min	Тур	Max	Unit
OFF CHARACTERISTICS		•	•		
Collector–Base Cutoff Current $(V_{CB} = 50 \text{ V}, I_E = 0)$	I _{CBO}	_	_	100	nAdc
Collector–Emitter Cutoff Current $(V_{CE} = 50 \text{ V}, I_B = 0)$	I _{CEO}	_	-	500	nAdc
Emitter-Base Cutoff Current (V _{EB} = 6.0 V, I _C = 0)	I _{EBO}	_	_	1.5	mAdc
Collector-Base Breakdown Voltage (I _C = 10 µA, I _E = 0)	V _(BR) CBO	50	-	-	Vdc
Collector-Emitter Breakdown Voltage (Note 6) (I _C = 2.0 mA, I _B = 0)	V _(BR) CEO	50	_	-	Vdc
ON CHARACTERISTICS		•			
DC Current Gain (Note 6) (I _C = 5.0 mA, V _{CE} = 10 V)	h _{FE}	15	27	-	
Collector-Emitter Saturation Voltage (Note 6) (I _C = 10 mA, I _B = 1.0 mA)	V _{CE(sat)}	_	_	0.25	Vdc
Input Voltage (off) ($V_{CE} = 5.0 \text{ V}, I_{C} = 100 \mu\text{A}$)	V _{i(off)}	_	1.2	-	Vdc
Input Voltage (on) (V _{CE} = 0.2 V, I _C = 20 mA)	V _{i(on)}	_	2.8	-	Vdc
Output Voltage (on) (V _{CC} = 5.0 V, V _B = 2.5 V, R _L = 1.0 k Ω)	V _{OL}	-	-	0.2	Vdc
Output Voltage (off) ($V_{CC} = 5.0 \text{ V}, V_B = 0.25 \text{ V}, R_L = 1.0 \text{ k}\Omega$)	V _{OH}	4.9	_	-	Vdc
Input Resistor	R1	3.3	4.7	6.1	kΩ
Resistor Ratio	R ₁ /R ₂	0.8	1.0	1.2	

^{6.} Pulsed Condition: Pulse Width = 300 msec, Duty Cycle \leq 2%.

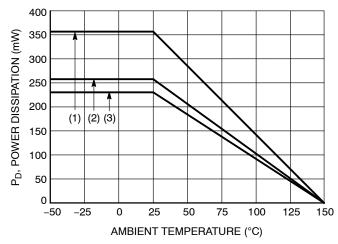


Figure 1. Derating Curve

- (1) SOT-363; 1.0 x 1.0 inch Pad
- (2) SOT-563; Minimum Pad
- (3) SOT-963; 100 mm², 1 oz. copper trace

TYPICAL CHARACTERISTICS MUN5132DW1, NSBA143EDXV6

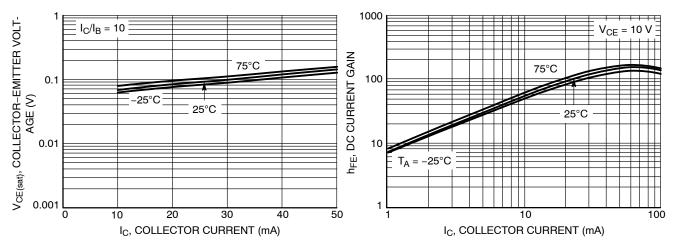


Figure 2. V_{CE(sat)} vs. I_C

Figure 3. DC Current Gain

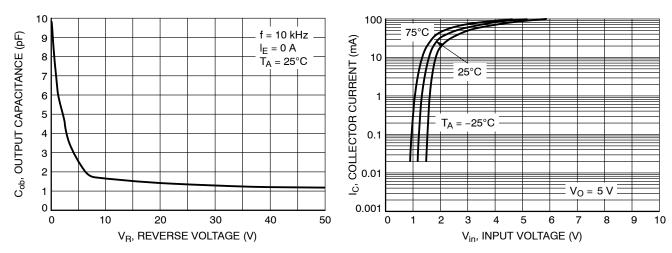


Figure 4. Output Capacitance

Figure 5. Output Current vs. Input Voltage

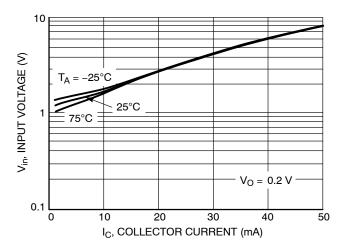


Figure 6. Input Voltage vs. Output Current

TYPICAL CHARACTERISTICS NSBA143EDP6

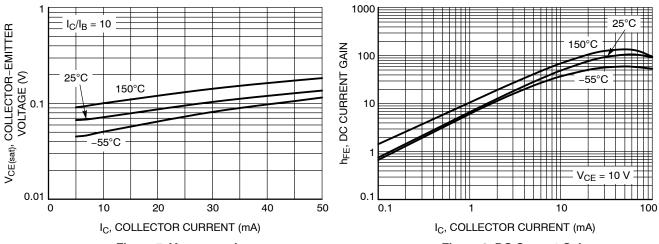


Figure 7. V_{CE(sat)} vs. I_C

Figure 8. DC Current Gain

-55°C

V_O = 5 V

6

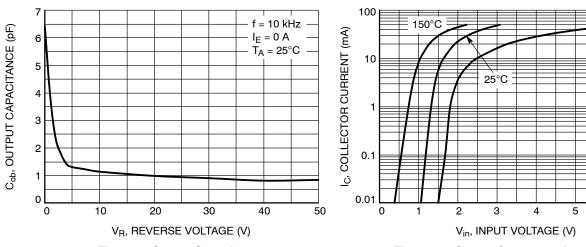


Figure 9. Output Capacitance

Figure 10. Output Current vs. Input Voltage

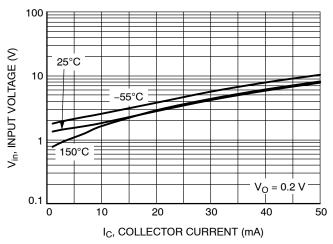


Figure 11. Input Voltage vs. Output Current



MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS



SC-88 2.00x1.25x0.90, 0.65P CASE 419B-02 **ISSUE Z**

DATE 18 APR 2024

MILLIMETERS

NOM

0.90

0.20

0.15

2.00 BSC

2.10 BSC

1.25 BSC

MAX.

1.10

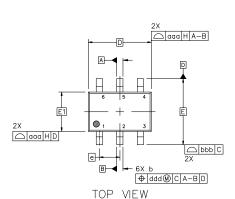
0.10

1.00

0.25

0.22

0.46



NOTES:

- DIMENSIONING AND TOLERANCING CONFORM TO ASME Y14.5-2018.
- ALL DIMENSION ARE IN MILLIMETERS.
- DIMENSIONS D AND E1 DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.20 PER END.
- DIMENSIONS D AND E1 AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY AND DATUM H.
 DATUMS A AND B ARE DETERMINED AT DATUM H.
- DIMENSIONS 6 AND C APPLY TO THE FLAT SECTION OF THE LEAD BETWEEN 0.08 AND 0.15 FROM THE TIP. 6.
- DIMENSION & DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 TOTAL IN EXCESS OF DIMENSION 6 AT MAXIMUM MATERIAL CONDITION. THE DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OF THE FOOT.

DIM

Α

Α1

Α2

b

С

D

Ε

F1

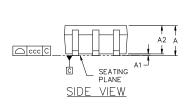
MIN

0.00

0.70

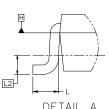
0.15

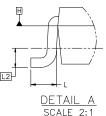
0.08



6X 0.30 -







GENERIC MARKING DIAGRAM*



е		0.65 BSC	,
L	0.26	0.36	
L2		0.15 BSC	
aaa	0.15		
bbb	0.30		
ccc	0.10		
ddd	0.10		

XXX = Specific Device Code

= Date Code*

= Pb-Free Package

RECOMMENDED MOUNTING FOOTPRINT* (Note: Microdot may be in either location)

6X 0.66

2.50

- *Date Code orientation and/or position may vary depending upon manufacturing location.
- *This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "■", may or may not be present. Some products may not follow the Generic Marking.

FOR ADDITIONAL INFORMATION ON OUR Pb-FREE

STYLES ON PAGE 2

DOCUMENT NUMBER:	98ASB42985B	Electronic versions are uncontrolled except when accessed directly from Printed versions are uncontrolled except when stamped "CONTROLLED	
DESCRIPTION:	SC-88 2.00x1.25x0.90, 0.65P		PAGE 1 OF 2

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STRATEGY AND SOLDERING DETAILS, PLEASE DOWNLOAD THE ONSEMI SOLDERING AND MOUNTING TECHNIQUES REFERENCE MANUAL, SOLDERRM/D.

SC-88 2.00x1.25x0.90, 0.65P CASE 419B-02 ISSUE Z

DATE 18 APR 2024

STYLE 1: PIN 1. EMITTER 2 2. BASE 2 3. COLLECTOR 1 4. EMITTER 1 5. BASE 1 6. COLLECTOR 2	STYLE 2: CANCELLED	STYLE 3: CANCELLED	STYLE 4: PIN 1. CATHODE 2. CATHODE 3. COLLECTOR 4. EMITTER 5. BASE 6. ANODE	STYLE 5: PIN 1. ANODE 2. ANODE 3. COLLECTOR 4. EMITTER 5. BASE 6. CATHODE	STYLE 6: PIN 1. ANODE 2 2. N/C 3. CATHODE 1 4. ANODE 1 5. N/C 6. CATHODE 2
STYLE 7: PIN 1. SOURCE 2 2. DRAIN 2 3. GATE 1 4. SOURCE 1 5. DRAIN 1 6. GATE 2	STYLE 8: CANCELLED	STYLE 9: PIN 1. EMITTER 2 2. EMITTER 1 3. COLLECTOR 1 4. BASE 1 5. BASE 2 6. COLLECTOR 2	STYLE 10: PIN 1. SOURCE 2 2. SOURCE 1 3. GATE 1 4. DRAIN 1 5. DRAIN 2 6. GATE 2	STYLE 11: PIN 1. CATHODE 2 2. CATHODE 2 3. ANODE 1 4. CATHODE 1 5. CATHODE 1 6. ANODE 2	STYLE 12: PIN 1. ANODE 2 2. ANODE 2 3. CATHODE 1 4. ANODE 1 5. ANODE 1 6. CATHODE 2
STYLE 13: PIN 1. ANODE 2. N/C 3. COLLECTOR 4. EMITTER 5. BASE 6. CATHODE	STYLE 14: PIN 1. VREF 2. GND 3. GND 4. IOUT 5. VEN 6. VCC	STYLE 15: PIN 1. ANODE 1 2. ANODE 2 3. ANODE 3 4. CATHODE 3 5. CATHODE 2 6. CATHODE 1	STYLE 16: PIN 1. BASE 1 2. EMITTER 2 3. COLLECTOR 2 4. BASE 2 5. EMITTER 1 6. COLLECTOR 1	STYLE 17: PIN 1. BASE 1 2. EMITTER 1 3. COLLECTOR 2 4. BASE 2 5. EMITTER 2 6. COLLECTOR 1	STYLE 18: PIN 1. VIN1 2. VCC 3. VOUT2 4. VIN2 5. GND 6. VOUT1
STYLE 19: PIN 1. I OUT 2. GND 3. GND 4. V CC 5. V EN 6. V REF	STYLE 20: PIN 1. COLLECTOR 2. COLLECTOR 3. BASE 4. EMITTER 5. COLLECTOR 6. COLLECTOR	STYLE 21: PIN 1. ANODE 1 2. N/C 3. ANODE 2 4. CATHODE 2 5. N/C 6. CATHODE 1	STYLE 22: PIN 1. D1 (i) 2. GND 3. D2 (i) 4. D2 (c) 5. VBUS 6. D1 (c)	STYLE 23: PIN 1. Vn 2. CH1 3. Vp 4. N/C 5. CH2 6. N/C	STYLE 24: PIN 1. CATHODE 2. ANODE 3. CATHODE 4. CATHODE 5. CATHODE 6. CATHODE
STYLE 25: PIN 1. BASE 1 2. CATHODE 3. COLLECTOR 2 4. BASE 2 5. EMITTER 6. COLLECTOR 1	STYLE 26: PIN 1. SOURCE 1 2. GATE 1 3. DRAIN 2 4. SOURCE 2 5. GATE 2 6. DRAIN 1	STYLE 27: PIN 1. BASE 2 2. BASE 1 3. COLLECTOR 1 4. EMITTER 1 5. EMITTER 2 6. COLLECTOR 2	STYLE 28: PIN 1. DRAIN 2. DRAIN 3. GATE 4. SOURCE 5. DRAIN 6. DRAIN	STYLE 29: PIN 1. ANODE 2. ANODE 3. COLLECTOR 4. EMITTER 5. BASE/ANODE 6. CATHODE	STYLE 30: PIN 1. SOURCE 1 2. DRAIN 2 3. DRAIN 2 4. SOURCE 2 5. GATE 1 6. DRAIN 1

Note: Please refer to datasheet for style callout. If style type is not called out in the datasheet refer to the device datasheet pinout or pin assignment.

DOCUMENT NUMBER:	98ASB42985B	Electronic versions are uncontrolled except when accessed directly from Printed versions are uncontrolled except when stamped "CONTROLLED"	
DESCRIPTION:	SC-88 2.00x1.25x0.90, 0.65P		PAGE 2 OF 2

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MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS



STYLE 1:

PIN 1. EMITTER 1 2. BASE 1

3. COLLECTOR 2

6 COLLECTOR 1

4. EMITTER 2

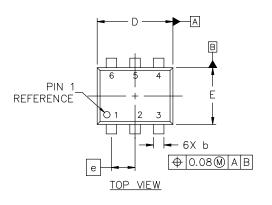
5. BASE 2

SOT-563-6 1.60x1.20x0.55, 0.50P CASE 463A **ISSUE J**

DATE 15 FEB 2024

NOTES:

- 1. DIMENSIONING AND TOLERANCING CONFORM TO ASME Y14.5-2018.
- ALL DIMENSION ARE IN MILLIMETERS.
- MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.



STYLE 2:

PIN 1. EMITTER 1

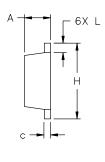
3. BASE 2

5. BASE 1

2. EMITTER 2

4. COLLECTOR 2

6. COLLECTOR 1



SIDE VIEW

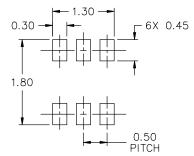
STYLE 3:

PIN 1. CATHODE 1 2. CATHODE 1

3. ANDDE/ANDDE 2 CATHODE 2

6. ANDDE/ANDDE 1

DIM	MILLIMETERS			
ויונע	MIN.	N□M.	MAX.	
А	0.50	0.55	0.60	
Ø	0.17	0.22	0.27	
	0.08	0.13	0.18	
D	1.50	1.60	1.70	
E	1.10	1,20	1.30	
е	0.50 BSC			
Ι	1.50	1.60	1.70	
Ĺ	0.10	0.20	0.30	



RECOMMENDED MOUNTING FOOTPRINT*

* FOR ADDITIONAL INFORMATION ON OUR Pb-FREE STRATEGY AND SOLDERING DETAILS, PLEASE DOWNLOAD THE ON SEMICONDUCTOR SOLDERING AND MOUNTING TECHNIQUES REFERENCE MANUAL, SOLDERRM/D.

STYLE 4: PIN 1. COLLECTOR 2. COLLECTOR STYLE 5: PIN 1. CATHODE 2. CATHODE STYLE 6: PIN 1. CATHODE 2. ANODE 3. BASE 3. ANDDE CATHODE 4. EMITTER 5. COLLECTOR 6. COLLECTOR 4. ANDDE 5. CATHODE 4. CATHODE 5. CATHODE 6. CATHODE CATHODE

STYLE 7: PIN 1. CATHODE 2. ANDDE 3. CATHODE 4. CATHODE 5. ANDDE 6. CATHODE	STYLE 8: PIN 1. DRAIN 2. DRAIN 3. GATE 4. SDURCE 5. DRAIN 6. DRAIN	STYLE 9: PIN 1. SDURCE 1 2. GATE 1 3. DRAIN 2 4. SDURCE 2 5. GATE 2 6. DRAIN 1
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STYLE 10: PIN 1. CATHODE 1 2. N/C	STYLE 11: PIN 1. EMITTER 2
3. CATHODE 2 4. ANODE 2 5. N/C 6. ANODE 1	3. COLLECTOR 1 4. EMITTER 1 5. BASE 1 6. COLLECTOR 2

GENERIC MARKING DIAGRAM*



XX = Specific Device Code M = Month Code

= Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

DOCUMENT NUMBER:	98AON11126D	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.	
DESCRIPTION:	SOT-563-6 1.60x1.20x0.55, 0.50P PAGE 1		PAGE 1 OF 1

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MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS



ISSUE F

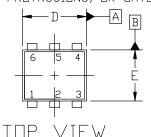


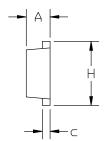
DATE 20 FEB 2024

NOTES:

- DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2018. 1.
- CONTROLLING DIMENSION: MILLIMETERS.
- MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.

 DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH,
- PROTRUSIONS, OR GATE BURRS

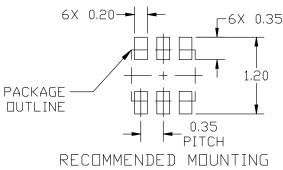




VIFW



MILLIMETERS DIM MIN. MAX. $N\square M$. 0.34 0.37 0.40 Α 0.10 0.15 0.20 h \subset 0.07 0.12 0.17 D 0.95 1.00 1.05 Ε 0.75 0.80 0.85 0.35 BSC 6 Н 1.00 1.05 0.95 0.19 REF L2 0.05 0.10 0.15



FOOTPRINT

*For additional information on our Pb-Free strategy and soldering details, please download the $\square N$ Semiconductor Soldering and Mounting Techniques Reference manual, SDLDERRM/D.

BUTTUM VIEW

STYLE 1: PIN 1. EMITTER 1 2. BASE 1 3. COLLECTOR 2 4. EMITTER 2 5. BASE 2	STYLE 2: PIN 1. E 2. E 3. E 4. C
 BASE 2 COLLECTOR 1 	5. E 6. C
STYLE 4:	STYLE 5:

PIN 1. COLLECTOR 2. COLLECTOR

3. BASE 4. EMITTER

STYLE 7: PIN 1. CATHODE 2. ANODE 3. CATHODE 4. CATHODE

5. ANODE 6. CATHODE

2. N/C 3. CATHODE 2

4. ANODE 2

5. N/C

STYLE 10: PIN 1. CATHODE 1

5 COLLECTOR

6. COLLECTOR

LE 2:	
N 1. EMITTER 1	
2. EMITTER2	
3. BASE 2	
4. COLLECTOR 2	
5. BASE 1	
6. COLLECTOR 1	

PIN 1. CATHODE 2. CATHODE 3. ANODE 4. ANODE

STYLE 8: PIN 1. DRAIN 2. DRAIN

5. CATHODE 6. CATHODE

3. GATE 4. SOURCE

5. DRAIN 6. DRAIN

◆ | 0.08 | A | B

6X L

STYLE 3:
PIN 1. CATHODE 1
CATHODE 1
ANODE/ANODE 2
CATHODE 2
CATHODE 2
6. ANODE/ANODE 1

STYLE 6:
PIN 1. CATHODE
ANODE
CATHODE
CATHODE
CATHODE
6 CATHODE

6. CATHODE
STYLE 9:
PIN 1. SOURCE 1
GATE 1
3. DRAIN 2
SOURCE 2
5. GATE 2
DRAIN 1

GENERIC MARKING DIAGRAM*



XX = Specific Device Code = Month Code

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "=", may or may not be present. Some products may not follow the Generic Marking.

DESCRIPTION:	SOT-963 1.00x1.00x0.37, 0.35P		PAGE 1 OF 1
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